



PK460 (v1.0) May 20, 2011

100% Material Declaration Data Sheet CSG484 for Spartan-6 FPGAs

Average Weight: 1.2740 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.033116	2.599%
	Silicon	7440-21-3	100.00		0.033116	
Die Attach Material					0.010225	0.803%
	Silver	7440-22-4	77.50		0.007924	
	Bismaleimide monomer	Trade Secret	15.00		0.001534	
	Acrylate monomer	Trade Secret	7.50		0.000767	
Mold Compound					0.472284	37.071%
	Solid Epoxy Resin	Trade Secret	5.00		0.023614	
	Phenol Resin	Trade Secret	5.00		0.023614	
	Fused Silica	60676-86-0	87.45		0.413012	
	Metal Hydroxide	Trade Secret	2.00		0.009446	
	Carbon Black	1333-86-4	0.55		0.002598	
Gold Wire					0.016904	1.327%
	Gold	7440-57-5	99.05		0.016743	
	Palladium	7440-05-3	0.95		0.000161	
	Calcium	7440-70-2	0.00		0.000000	
Solder Balls					0.171033	13.425%
	Tin	7440-31-5	96.50		0.165047	
	Silver	7440-22-4	3.00		0.005131	
	Copper	7440-50-8	0.50		0.000855	
Substrate					0.570438	44.775%
	Copper	7440-50-8	45.61		0.260162	
	Nickel	7440-02-0	0.96		0.005488	
	Gold	7440-57-5	0.16		0.000936	
	BT (core)	21645-51-2/ 7440-50-8/ Epoxy resin	48.94		0.279192	
	Solder mask	14807-96-6/ 7727-43-7/ 7631- 86-9/ 34590-94-8/ 85954-11-6	4.32		0.024660	

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Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
5/20/11	1.0	Initial Xilinx release.

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